



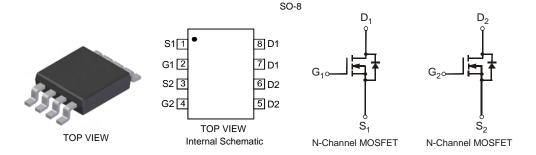
DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Lead Free By Design/RoHS Compliant (Note 1)
- "Green" Device (Note 2)
- Qualified to AEC-Q101 Standards for High Reliability

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals Connections: See Diagram
- Terminals: Finish Matte Tin annealed over Copper lead frame. Solderable per MIL-STD-202, Method 208
- Marking Information: See Page 4
- Ordering Information: See Page 4
- Weight: 0.072 grams (approximate)



Maximum Ratings @T_A = 25°C unless otherwise specified

Chara	acteristic		Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	20	V
Gate-Source Voltage			V _{GSS}	±12	V
Drain Current (Note 3)	Steady State	$T_A = 25$ °C $T_A = 85$ °C	I _D	7.63 4.92	А
Pulsed Drain Current (Note 4)			I _{DM}	30	А

Thermal Characteristics

Characteristic	Symbol	Value	Unit
Total Power Dissipation (Note 3)	P _D	1.16	W
Thermal Resistance, Junction to Ambient @T _A = 25°C	$R_{ heta JA}$	107.4	°C/W
Operating and Storage Temperature Range	$T_{J,}T_{STG}$	-55 to +150	°C

Notes:

- 1. No purposefully added lead.
- Diodes Inc.'s "Green" policy can be found on our website at http://www.diodes.com/products/lead_free/index.php.
- 3. Device mounted on FR-4 PCB with minimum recommended pad layout.
- 4. Repetitive rating, pulse width limited by function temperature.

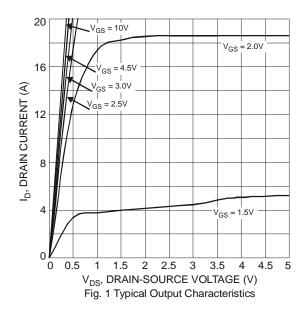


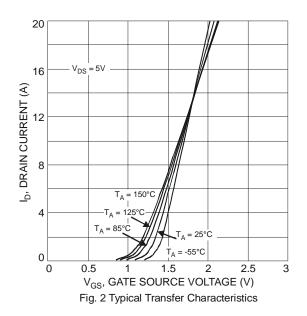
Electrical Characteristics @T_A = 25°C unless otherwise specified

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 5)						
Drain-Source Breakdown Voltage	BV _{DSS}	20	-	-	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current TJ = 25°C	I _{DSS}	-	-	1	μΑ	$V_{DS} = 20V$, $V_{GS} = 0V$
Gate-Source Leakage	I _{GSS}	-	-	±100	nA	$V_{GS} = \pm 12V, V_{DS} = 0V$
ON CHARACTERISTICS (Note 5)						
Gate Threshold Voltage	V _{GS(th)}	0.5	-	1.2	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$
Static Drain-Source On-Resistance	D	-	19	28	$m\Omega$	$V_{GS} = 4.5V, I_D = 6.0A$
Static Drain-Source On-Resistance	R _{DS (ON)}		25	41		$V_{GS} = 2.5V, I_D = 5.2A$
Forward Transfer Admittance	Y _{fs}	-	6	-	S	$V_{DS} = 10V, I_D = 6A$
Diode Forward Voltage	V_{SD}	-	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1.7A$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C _{iss}	-	550	-		$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz
Output Capacitance	Coss	-	88	-	pF	
Reverse Transfer Capacitance	Crss	-	81	-		
Gate Resistance	R_g	-	1.34	-	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$
Total Gate Charge (10V)	Qg		15.6	-	nC	$V_{GS} = 10V, V_{DS} = 10V,$ $I_D = 6.0A$
Total Gate Charge (4.5V)	Q_{g}	-	7.2	-		$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{V},$ $I_D = 6.0 \text{A}$
Gate-Source Charge	Q_{gs}	-	1.0	-	nC	
Gate-Drain Charge	Q_{gd}	-	1.9	-		
Turn-On Delay Time	t _{D(on)}	-	4.69	-		$V_{DD} = 10V, V_{GEN} = 4.5V,$ $R_g = 1\Omega, I_D = 6.7A$
Turn-On Rise Time	t _r	-	13.19	-	no	
Turn-Off Delay Time	$t_{D(off)}$	-	22.10	-	ns	
Turn-Off Fall Time	t _f	-	6.43	-		

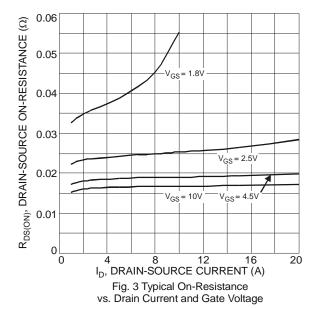
Notes:

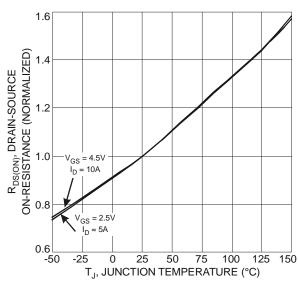
- $5. \ Short \ duration \ pulse \ test \ used \ to \ minimize \ self-heating \ effect.$
- 6. Guaranteed by design. Not subject to production testing.

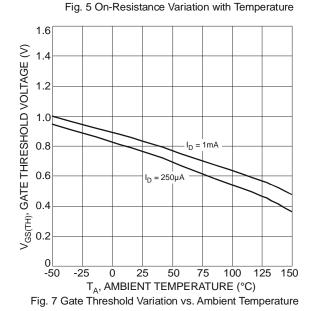












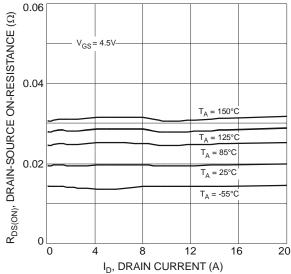


Fig. 4 Typical Drain-Source On-Resistance vs. Drain Current and Temperature

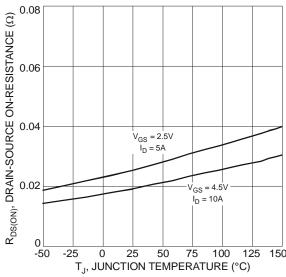


Fig. 6 On-Resistance Variation with Temperature

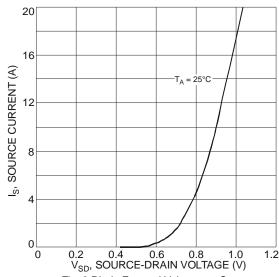
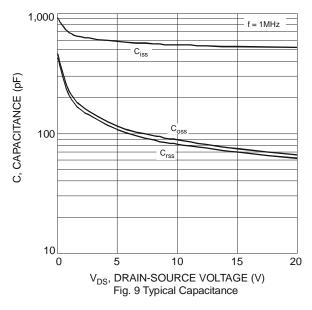


Fig. 8 Diode Forward Voltage vs. Current





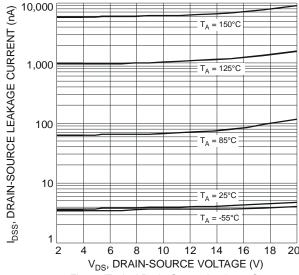


Fig. 10 Typical Drain-Source Leakage Current vs. Drain-Source Voltage

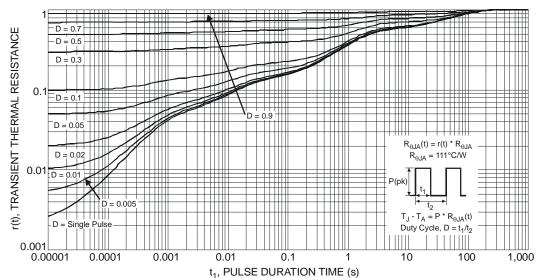


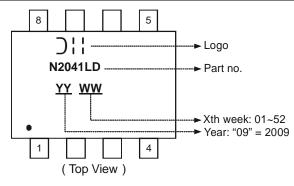
Fig. 11 Transient Thermal Response

Ordering Information (Note 7)

Part Number	Case	Packaging
DMN2041LSD-13	SO-8	2500/Tape & Reel

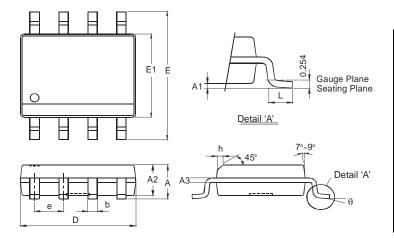
Notes: 7. For packaging details, go to our website at http://www.diodes.com/datasheets/ap02007.pdf.

Marking Information



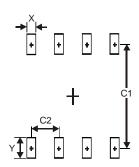


Package Outline Dimensions



SO-8				
Dim	Min	Max		
Α	-	1.75		
A1	0.10	0.20		
A2	1.30	1.50		
А3	0.15	0.25		
b	0.3	0.5		
D	4.85	4.95		
Е	5.90	6.10		
E1	3.85	3.95		
е	1.27 Typ			
h	-	0.35		
L	0.62	0.82		
θ	0°	8°		
All Dimensions in mm				

Suggested Pad Layout



Dimensions	Value (in mm)
X	0.60
Y	1.55
C1	5.4
C2	1.27



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